**Association of Powder Process Industry and Engineering, JAPAN**

**Modeling and Simulation Division**

**APPIE Computational Granular Mechanics Award 2026**

Send a **single** electronic (PDF file preferred) copy of this form, supplemental sheets, supporting letters and other relevant documents via email to: **Modeling and Simulation (M&S) Division Secretariat.**

E-mail: award@funtai.jp

**Deadline for complete package: January 31, 2026**

# Registration information

|  |  |
| --- | --- |
| **Name of Nominee** |  |
| **Present Position** |  |
| **Institution** |  |
| **Telephone Number** |  |
| **Email** |  |
| **Address** |  |
| **Education (Degree, Major, Year)** |  |

Date \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

Nominator’s Signature\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

|  |
| --- |
| **Selected bibliography** |
| **Selected papers****(Max.10)** |  |
| **Selected invited lectures****(Max.10)** |  |
| **Awards, Other Contributions** |  |

**SUPPORTING LETTERS**

Two letters of support should be attached, and the names of the supporters are listed below.

|  |  |
| --- | --- |
| **Name** | **Affiliation** |
|  |  |
|  |  |

**AWARD PRESENTATION TITLE**

Write the award title (as stated in the commendation) below.

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**M&S Division Secretariat** E-mail: award@funtai.jp

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Personal information obtained from submitted documents will be used for selection, contacting applicants, notification of selection results, and administrative work. Except as permitted by law, personal information will not be used for purposes other than those listed above without the consent of the applicant.